

AMENDMENTS TO THE CLAIMS

Claim 1 (currently amended): A process for pattern formation comprising the steps of:
coating a carrier with a photosensitive material,
~~exposure of~~ exposing the photosensitive material to a pattern of radiation, and
physically transferring ~~of~~ the exposed material to a substrate.

Claim 2 (currently amended): The process of claim 1, further comprising the step of
development of developing the exposed photosensitive material after the
material is transferred to the substrate.

Claim 3 (original): The process of claim 2, in which the substrate is a curved surface, and
the carrier is manufactured from a flexible material.

Claim 4 (original): The process of claim 1, in which
the carrier is fabricated from the group of materials consisting of quartz, glass,
silicon dioxide, silicon nitride, sodium chloride, silicon, and gallium arsenide.

Claim 5 (original): The process of claim 1, in which
the carrier is fabricated from a polymeric material.

Claim 6 (original): The process of claim 1, in which the
photosensitive material is a photoresist.

Claim 7 (currently amended): The process of claim 1, in which
the ~~exposure~~ exposing step comprises exposure to UV photons.

Claim 8 (currently amended): The process of claim 1, in which the
photosensitive material is sensitive to electron beam exposure, and the
~~exposure~~ exposing step comprises exposure to electron beams.

Claim 9 (currently amended): The process of claim 1, ~~in which~~ further comprising the step of
~~an adhesion layer is added to coating~~ the photosensitive material on the carrier
with an adhesion layer.

Claim 10 (original): The process of claim 9, in which
a removal layer is formed between the carrier and the photosensitive material.

Claim 11 (currently amended): The process of claim ~~10-9~~, in which
the adhesion layer comprises multiple layers.

Claim 12 (currently amended): The process of claim 1, ~~in which~~ further comprising the step of
~~an adhesion layer is added to coating~~ the substrate with an adhesion layer.

Claim 13 (original): The process of claim 12, in which
a removal layer is formed between the carrier and the photosensitive material.

Claim 14 (original): The process of claim 12, in which
the adhesion layer comprises multiple layers.

Claim 15 (currently amended): The process of claim 14, ~~in which~~ further comprising the step of
~~an additional adhesion layer is added to coating~~ the photosensitive material with an
additional adhesion layer.

Claim 16 (original): The process of claim 15, in which
the additional adhesion layer comprises multiple layers.

Claim 17 (currently amended): The process of claim 1 in which
the step of transferring of the photosensitive material to the substrate comprises
bringing the carrier with the material in close physical proximity to the substrate
and pressing the carrier, substrate, and intervening films together.

Claim 18 (original): The process of claim 17, in which
the carrier and the substrate are heated above room temperature while in close
physical proximity.

Claim 19 (original): The process of claim 17, in which
the carrier and substrate are exposed to radiation while in close physical proximity.

Claim 20 (original): The process of claim 19, in which
the radiation comprises UV photons.

Claim 21 (original): The process of claim 17, in which
a solvent is introduced to dissolve a part of the intervening films.

Claim 22 (currently amended): The process of claim 17, ~~including the additional further~~
comprising the step of
performing an alignment between the carrier and the substrate.

Claim 23 (currently amended): The process of claim 17, ~~including the additional further~~
comprising the step of
performing an alignment between the exposed material and the substrate.

Claim 24 – 27 (canceled).